

Title (en)

THERMAL MANAGEMENT FOR ADDITIVE PRINTED CIRCUITS

Title (de)

THERMISCHE KONTROLLE FÜR MIT ADDITIVEN BEDRUCKTE SCHALTUNGEN

Title (fr)

GESTION THERMIQUE POUR CIRCUITS IMPRIMES ADDITIFS

Publication

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Application

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Abstract (en)

[origin: WO9611105A1] A heat dissipating assembly for mounting heat generating electronic components is described. The invention comprises a thermally conductive fiber reinforced polymeric resin sheet containing thermally conductive fillers and having planar surfaces, an additive printed circuit board and a metal heat sink having at least one planar surface. Because the dielectric surfaces and conductors of additive printed circuit boards are coplanar, intimate contact between the planar surfaces of the thermally conductive resin sheet, the printed circuit board surface and the metal heat sink is maintained without intermediate voids, thereby significantly enhancing heat transfer from the printed circuit board to the metal heat sink.

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